



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Commissioner for Patents
Washington, D.C. 20231

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on February 18, 2003

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Harold C. Moore

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[Signature]
Signature

February 18, 2003

Date of Signature

*Entered
Inclusion
4/16/03*

Re: Application of: Newell E. Chiesl
Serial No.: 09/960,441
Filed: September 21, 2001
Confirmation No.: 5776
For: Arrangement for Measuring Pressure on a
Semiconductor Wafer and an Associated
Method for Fabricating a Semiconductor
Wafer
03/04/2003 ASMITH 00000005 130014 09960441
01 FC:1201 84.00 CH Group Art Unit: 2812
02 FC:1202 126.00 CH Examiner: Viktor Simkovic
Our Docket: 1003-0610

Adjustment date: 07/29/2003 SDIRETA1
03/04/2003 ASMITH 00000005 130014 09960441
02 FC:1202 126.00 CR

RESPONSE TO OFFICE ACTION

Sir:

In response to the Office Action dated November 18, 2002 for the above-identified
patent application, please amend the application as follows: